In the Claims:

Kindly amend the claims as follows:

Claims 2-6 are cancelled without prejudice.

1. (Currently amended) A ~~silicon spring electrode~~ method for manufacturing an anisotropic conductive sheet comprising:

step A; etching through a monocrystal silicon wafer by a deep reactive ion etching so as to form a part having a bending leaf spring shape ~~formed out of a monocrystal silicon by anisotropic etching;~~ such that planes of said formed leaf spring are parallel to a cross section of said wafer,

step B; forming a silicon spring electrode by forming a conductive layer on ~~the surfaces~~ a surface of said ~~silicon spring electrode~~ part having the bending leaf spring shape formed in step A, and

step C; inserting a plurality of said silicon spring electrodes formed in step B respectively into through holes of a soft plastic sheet such that said spring electrodes are clamped and fixed to said soft plastic sheet.

2. (Cancelled)

3. (Cancelled)

4. (Cancelled)

5. (Cancelled)

6. (Cancelled)